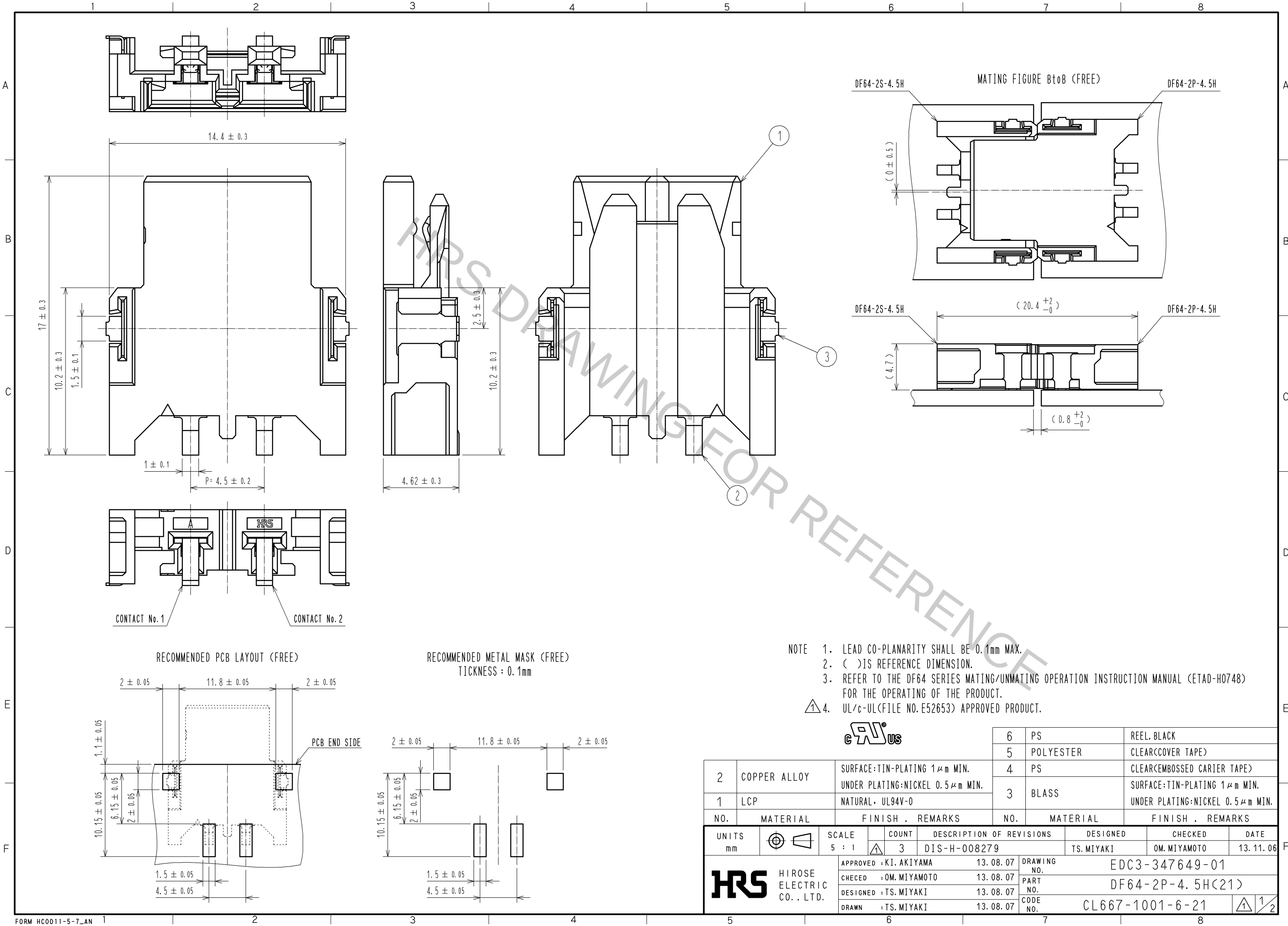
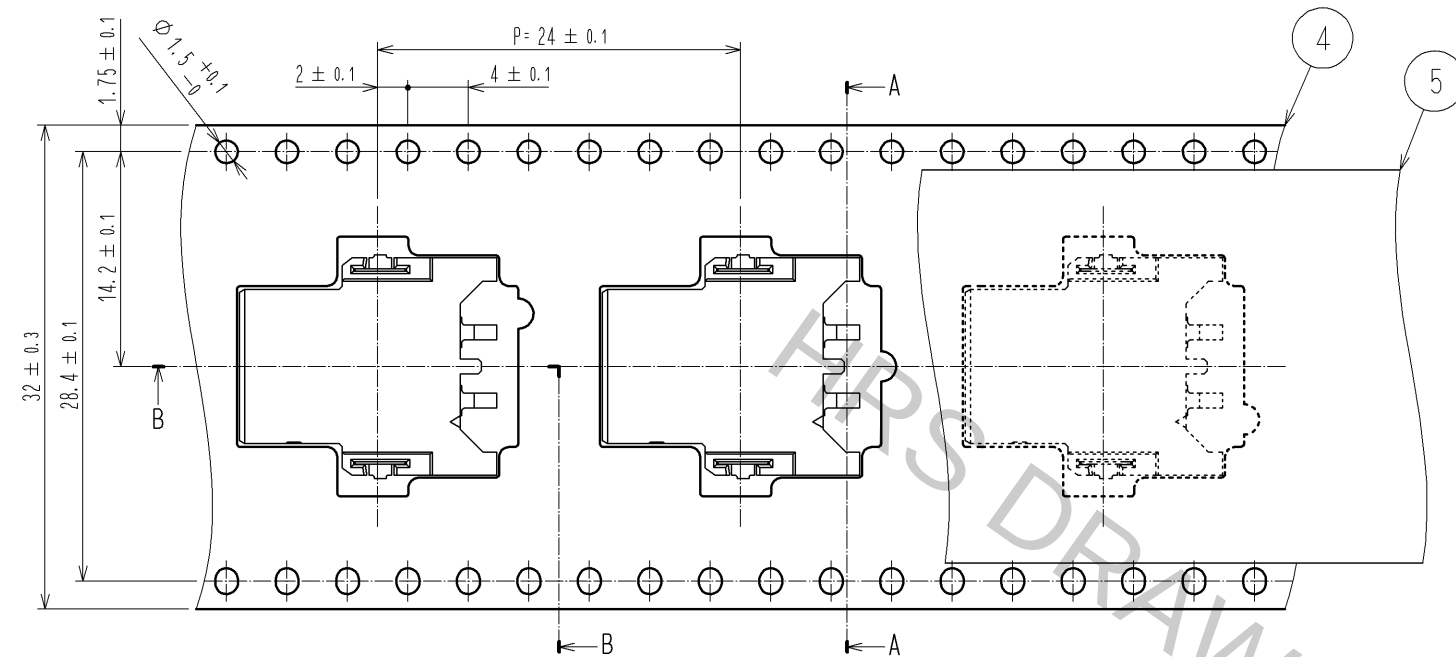
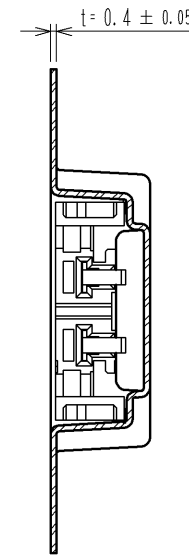




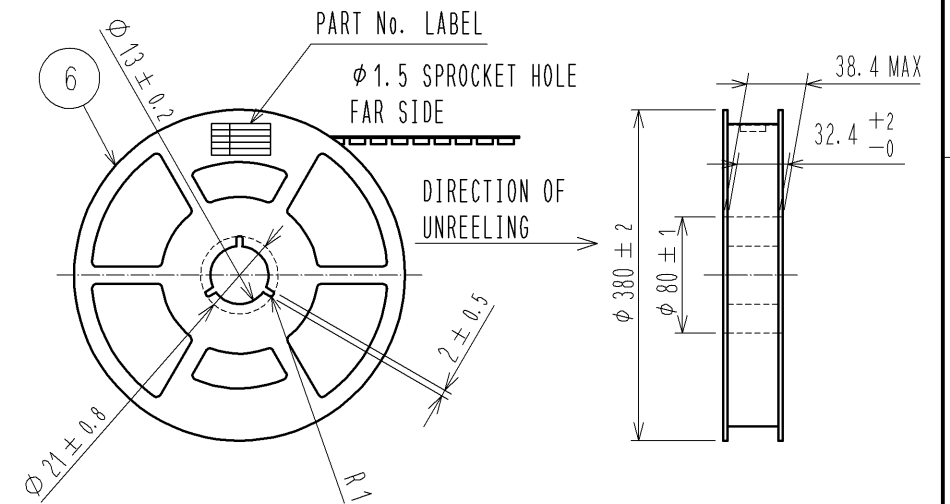
DRAWING FOR PACKING (2:1)



A-A(2:1)



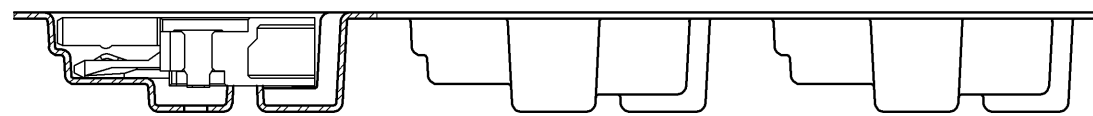
STYLE AND DIMENSION OF REEL(FREE)



DETAIL OF PART No. LABEL

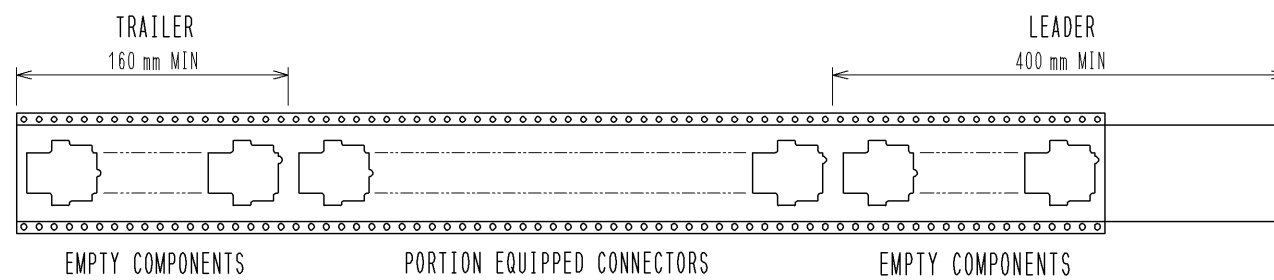
生産月日	年 月 日
図 番	CL667-1001-6-21
品 名	DF64-2P-4.5H(21)
納入数量	500 K0
納入者	ヒロセ電機(株)

B-B(2:1)



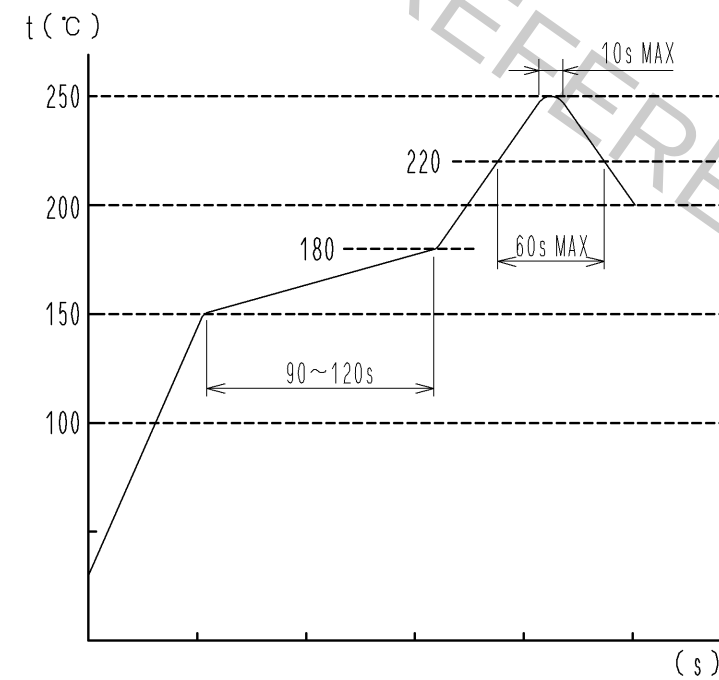
DIRECTION OF REELING →

① ⑥ TAPING(FREE)



- ① NOTE 5. 1REEL:500 CONNECTORS.
⑥ REEL TO JIS C 0806.(PACKAGING OF COMPONENTS FOR AUTOMATING HANDLING)
7. () IS REFERENCE DIMENSION.

REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE (REFERENCE)



NUMBER OF REFLOW CYCLES 2 CYCLES MAX
THE TEMPERATURE IS MEASURED IN THE TERMINAL LEAD PART.
ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE,
PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT
THE PROFILE.
THEREFOR, A THOROUGH EVALUATION OF MOUNTING CONDITION IS
REQUIRED PRIOR TO PRODUCTION.
TEMPERATURE IS MEASURED AT CONTACT LEAD.

HRS

DRAWING NO.	EDC3-347649-01
PART NO.	DF64-2P-4.5H(21)
CODE NO.	CL667-1001-6-21

① ② ③